

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPD30N06S2L-23	**Issued**	12. May 2021
MA#	MA001811464		
Package	PG-TO252-3-11	**Weight***	370.75 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.544	0.69	0.69	6863	6863
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		174	
	non noble metal	iron	7439-89-6	0.215	0.06		581	
	non noble metal	copper	7440-50-8	215.017	57.99	58.07	579957	580712
wire	non noble metal	aluminium	7429-90-5	1.429	0.39	0.39	3855	3855
encapsulation	inorganic material	zincoxide	1314-13-2	1.262	0.34		3403	
	miscellaneous	miscellaneous	-	6.308	1.70		17014	
	plastics	epoxy resin	-	18.923	5.10		51041	
	inorganic material	silicondioxide	60676-86-0	99.662	26.88	34.02	268816	340274
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10088	10088
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	245	246
solder	non noble metal	tin	7440-31-5	0.046	0.01		123	
	noble metal	silver	7440-22-4	0.057	0.02		154	
	non noble metal	lead	7439-92-1	2.184	0.59	0.62	5890	6167
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			16	
	non noble metal	iron	7439-89-6	0.019	0.01		52	
	non noble metal	copper	7440-50-8	19.177	5.17	5.18	51727	51795
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com